

ABSTRACT

In a multi-layer printed wiring board 100 comprising single side circuit boards A, B and for accommodating an IC chip 70, BGAs 56 are disposed on its front and rear faces, so that with an IC module 120 mounted through the BGA 56 on the front face, this board can be connected to a printed wiring board through the BGA 56 on the rear face. Thus, freedom in the configuration of the IC module mounted increases so that various kinds of the IC modules can be loaded.

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